Feed-through header - MCV 1,5/ 8-GF-3,5 GY - 1229121

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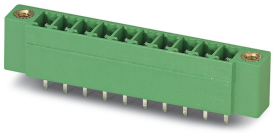

The figure shows a 10-position version of the product

PCB header, nominal cross section: 1.5 mm², color: gray, nominal current: 8 A, rated voltage (III/2): 160 V, contact surface: Tin, type of contact: Male connector, Number of rows: 1, Number of positions per row: 8, product range: MCV 1,5/..-GF, pitch: 3.5 mm, mounting: Wave soldering, pin layout: Linear pinning, solder pin [P]: 3.4 mm, plug-in system: MINI COMBICON, Locking: Screw locking, type of packaging: packed in cardboard

Your advantages

- Well-known mounting principle allows worldwide use
- Screwable flange for superior mechanical stability
- Vertical connection enables multi-row arrangement on the PCB
- Maximum flexibility when it comes to device design – one header for connectors with different connection technologies

Key Commercial Data

Packing unit	1
GTIN	4 063151 325800
GTIN	4063151325800
Custom tariff number	85366930

Technical data

Item properties

Brief article description	Feed-through header
Plug-in system	MINI COMBICON
Type of contact	Male connector
Range of articles	MCV 1,5/..-GF
Pitch	3.5 mm
Number of positions	8

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Technical data

Item properties

Mounting type	Wave soldering
Pin layout	Linear pinning
Number of levels	1
Pin connector pattern alignment	Standard

Electrical parameters

Nominal current	8 A
Nom. voltage	160 V
Rated voltage (III/3)	160 V
Rated voltage (III/2)	160 V
Rated voltage (II/2)	250 V
Rated surge voltage (III/3)	2.5 kV
Rated surge voltage (III/2)	2.5 kV
Rated surge voltage (II/2)	2.5 kV

Material data - contact

Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/ JEDEC JESD 201
Contact material	Cu alloy
Surface characteristics	Tin-plated
Metal surface contact area (top layer)	Tin (3 - 5 µm Sn)
Metal surface contact area (middle layer)	Nickel (1 - 3 µm Ni)
Metal surface soldering area (top layer)	Tin (3 - 5 µm Sn)
Metal surface soldering area (middle layer)	Nickel (1 - 3 µm Ni)

Material data - housing

Housing color	gray (7042)
Insulating material	PBT
Insulating material group	IIIa
CTI according to IEC 60112	225
Flammability rating according to UL 94	V0

Flange specifications

Type of locking	Screw locking
Mounting flange	Threaded flange
Torque	0.3 Nm

Dimensions for the product

Caption	Schematische Abbildung - weitere Details siehe Produktfamilienzeichnung im Download Center
Length [l]	7.25 mm

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Technical data

Dimensions for the product

Width [w]	38.3 mm
Height [h]	12.6 mm
Pitch	3.5 mm
Height (without solder pin)	9.2 mm
Solder pin [P]	3.4 mm
Pin dimensions	0.8 x 0.8 mm

Dimensions for PCB design

Hole diameter	1.2 mm

Packaging information

Type of packaging	packed in cardboard
Pieces per package	100
Denomination packing units	Pcs.

Ambient conditions

Ambient temperature (storage/transport)	-40 °C ... 70 °C
Ambient temperature (assembly)	-5 °C ... 100 °C
Ambient temperature (operation)	-40 °C ... 100 °C (dependent on the derating curve)

Air clearances and creepage distances

Clearances and creepage distances	IEC 60664-1:2007-04
Specification	IEC 60664-1:2007-04
Minimum clearance - inhomogeneous field (III/3)	1.5 mm
Minimum clearance - inhomogeneous field (III/2)	1.5 mm
Minimum clearance - inhomogeneous field (II/2)	1.5 mm
Minimum creepage distance value (III/3)	2.5 mm
Minimum creepage distance value (III/2)	1.6 mm
Minimum creepage distance value (II/2)	2.5 mm

Classifications

eCl@ss

eCl@ss 9.0	27440402